

WHAT IS CLAIMED IS:

1. An apparatus comprising:
an integrated circuit die comprising a conductive die pad;
a package comprising a conductive package pad; and
5 an interconnect comprising two or more stranded wires, a first end of the interconnect electrically coupled to the conductive die pad, and a second end of the interconnect electrically coupled to the package pad.
2. An apparatus according to Claim 1,
10 wherein the integrated circuit die further comprises a second conductive die pad,
wherein the package comprises a second conductive package pad, further comprising:
a second interconnect comprising two or more stranded wires, a first end of the second interconnect electrically coupled to the second conductive die pad, and a second end
15 of the second interconnect electrically coupled to the second package conductive pad.
3. An apparatus according to Claim 1, further comprising:
a second integrated circuit die comprising a second conductive die pad; and
a second interconnect comprising two or more stranded wires, a first end of the
20 second interconnect electrically coupled to the second conductive die pad, and a second end of the second interconnect electrically coupled to a second conductive package pad of the package.
4. An apparatus according to Claim 1, further comprising:

a second integrated circuit die comprising a third conductive die pad; and
a second interconnect comprising two or more stranded wires, a first end of the
second interconnect electrically coupled to a second conductive die pad of the integrated
circuit die, and a second end of the second interconnect electrically coupled to the third
5 conductive die pad.

5. An apparatus according to Claim 1,
wherein a shape of at least one of the two or more stranded wires is different from a
shape of at least one other of the two or more stranded wires.

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6. An apparatus according to Claim 5,
wherein a cross-sectional shape of the at least one of the two or more stranded wires
is different from a cross-sectional shape of the at least one other of the two or more stranded
wires.

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7. An interconnect comprising:
a first wire; and
a second wire,
a first end of the first wire and a first end of the second wire to bond to a conductive
20 die pad of an integrated circuit die substantially simultaneously, and
a second end of the first wire and a second end of the second wire to bond to a
conductive package pad of an integrated circuit package substantially simultaneously.

8. An interconnect according to Claim 7, wherein the first wire and the second wire
25 are stranded.

9. An interconnect according to Claim 8,
wherein a shape of the first wire is different from a shape of the second wire.

10. An interconnect according to Claim 9,
5 wherein a cross-sectional shape of the first wire is different from a cross-sectional
shape of the second wire.

11. A method comprising:
bonding a first wire and a second wire to a conductive die pad of an integrated circuit
10 die using a first bond; and
bonding the first wire and the second wire to a conductive package pad of an
integrated circuit package using a second bond.

12. A method according to Claim 11, wherein the two wires are stranded.
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13. A method according to Claim 12,
wherein a shape of the first wire is different from a shape of the second wire.

14. A method according to Claim 11,
20 wherein bonding the first wire and the second wire to the conductive die pad
comprises bonding a first end of the first wire and a first end of the second wire to the
conductive die pad substantially simultaneously, and
wherein bonding the first wire and the second wire to the conductive package pad
comprises bonding a second end of the first wire and a second end of the second wire to the
25 conductive package pad substantially simultaneously.

15. A system comprising:

an integrated circuit die comprising a conductive die pad;

a package comprising a conductive package pad;

5 an interconnect comprising two or more stranded wires, a first end of the interconnect electrically coupled to the conductive die pad, and a second end of the interconnect electrically coupled to the package pad; and

a double data rate memory electrically coupled to the package.

10 16. A system according to Claim 15, further comprising:

a motherboard coupled to the package and to the memory.

17. A system according to Claim 15, further comprising:

15 a second interconnect comprising two or more stranded wires, a first end of the second interconnect electrically coupled to a second conductive die pad of the integrated circuit die, and a second end of the second interconnect electrically coupled to a second package conductive pad of the package.

18. A system according to Claim 15, further comprising:

20 a second integrated circuit die comprising a second conductive die pad; and

a second interconnect comprising two or more stranded wires, a first end of the second interconnect electrically coupled to the second conductive die pad, and a second end of the second interconnect electrically coupled to a second conductive package pad of the package.

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19. A system according to Claim 15,
wherein a shape of at least one of the two or more stranded wires is different from a
shape of at least one other of the two or more stranded wires.